

先進解決方案高速直流電鍍銅柱技術

Advanced Solution for High Speed Direct Current Copper Pillar Technology



COPPER GLEAM™ CP360/CP370 Acid Copper

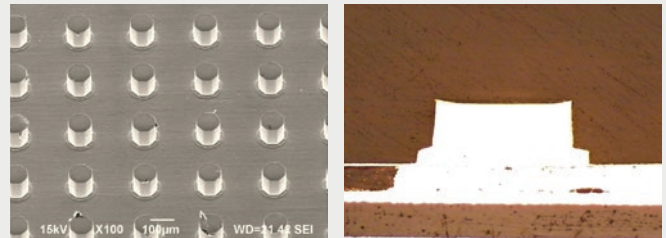
COPPER GLEAM™ CP360/CP370 Acid Copper is designed for copper pillar applications with high plating speed and excellent deposit uniformity. As a three-component system, chemical is able to fine tune deposit morphology across a wide variety of Cu pillar feature sizes, while maintaining with-in unit and with-in panel uniformity and void free performance.

COPPER GLEAM™ CP360/CP370 在銅柱電鍍應用上展現快速電鍍效率與優越的均勻性。三劑型藥水的使用方式，可輕易透過參數微調達到不同客戶需求，在兼顧unit和panel鍍銅均勻性的同時，仍具備良好的鍍銅品質。

Advantages 優點

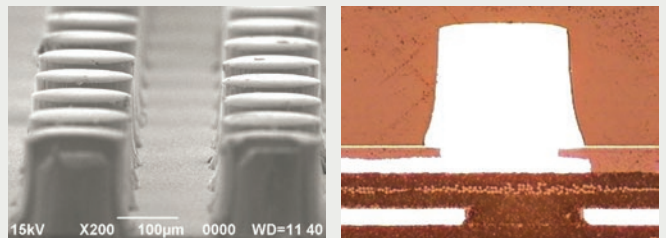
- Flat Pillar Top with Excellent Panel Uniformity
銅柱表面平整並有出色的全板面均勻性
- Can be Applied with Higher Current Density (5~10 ASD)
可搭配較高的操作電流 (5~10 ASD)
- Pure Deposition with Excellent Reliability Performance (ex: no K-voids)
高純度銅沉積，優良可靠性表現 (例如: 無K-空隙)
- Three Components Can be Analyzed by CVS
三種添加劑皆可用CVS分析

CP360 for pillar bump on flat panel



Dry Film open/height: 90/120 μ m
Copper pillar height: 100 μ m

CP370 for pillar bump on dent via



Dry film open/height: 170/150 μ m
Copper pillar height: 140 μ m